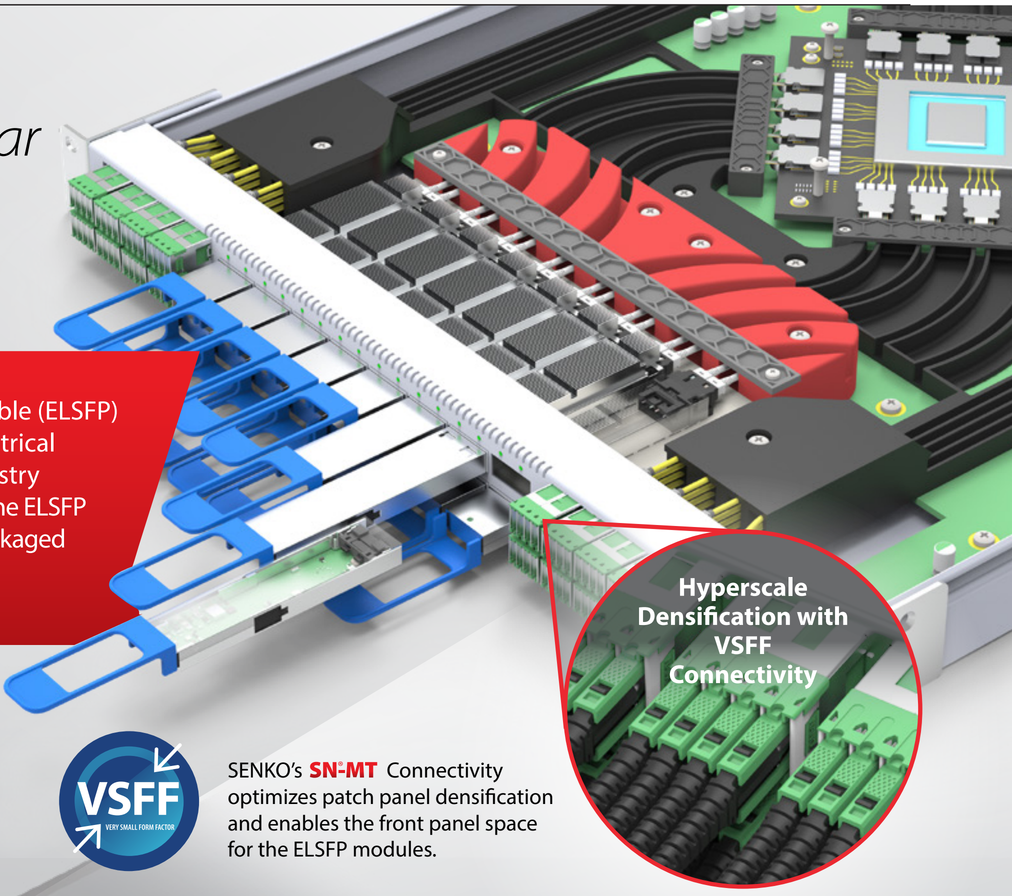
SENKO®
Advanced Components

Standardized by **OIF**

ELSFP *External Laser Small Form Factor Pluggable*

Eliminate CPO switch downtime with modular 'hot-swappable' laser sources

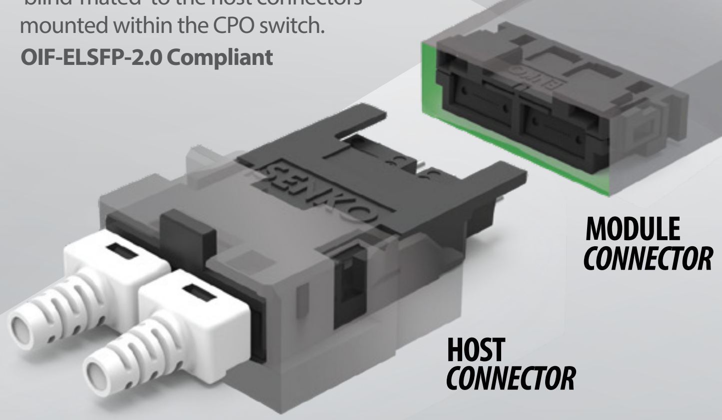


The External Laser Small Form-Factor Pluggable (ELSFP) is a pioneering blind-mating optical and electrical interconnect in a convenient pluggable industry recognized OSFP-RHS approximate footprint. The ELSFP is optimized to support next-generation co-packaged optics (CPO) requiring a remote laser source.

Module and Host Connectors

SENKO's innovative design allows the laser module to be quickly and easily 'blind-mated' to the host connectors mounted within the CPO switch.
OIF-ELSFP-2.0 Compliant

SENKO's **SN-MT** Connectivity optimizes patch panel densification and enables the front panel space for the ELSFP modules.



FEATURES

- Reduced overall system thermal power density
- Fast 'plug & play' design for fast deployment
- Compact design enables maximum face-plate density
- A single ELSFP can support multiple OEs
- Hot swappable to prevent system downtime
- Eye-safe design
- Approximate OSFP-RHS envelope
- PM fiber assemblies for the interconnect between
- ELSFP and CPO engines

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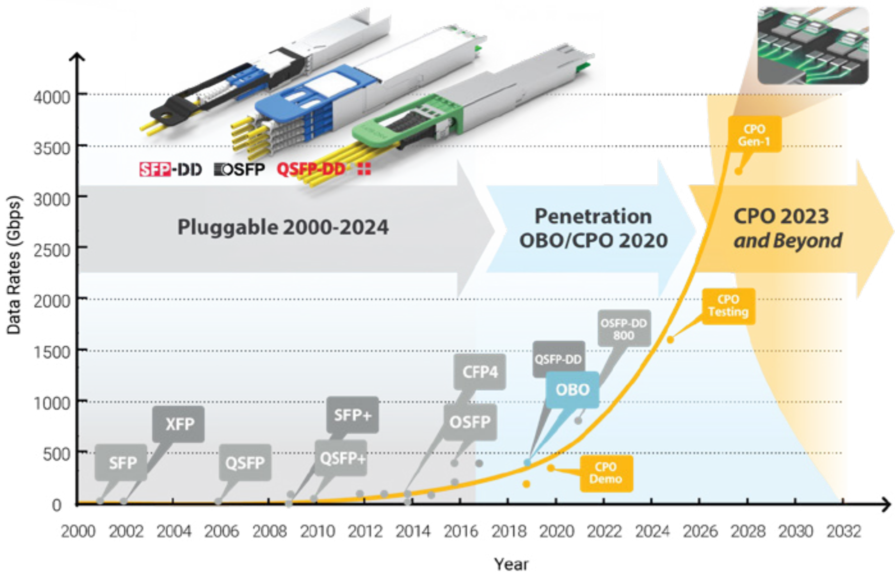
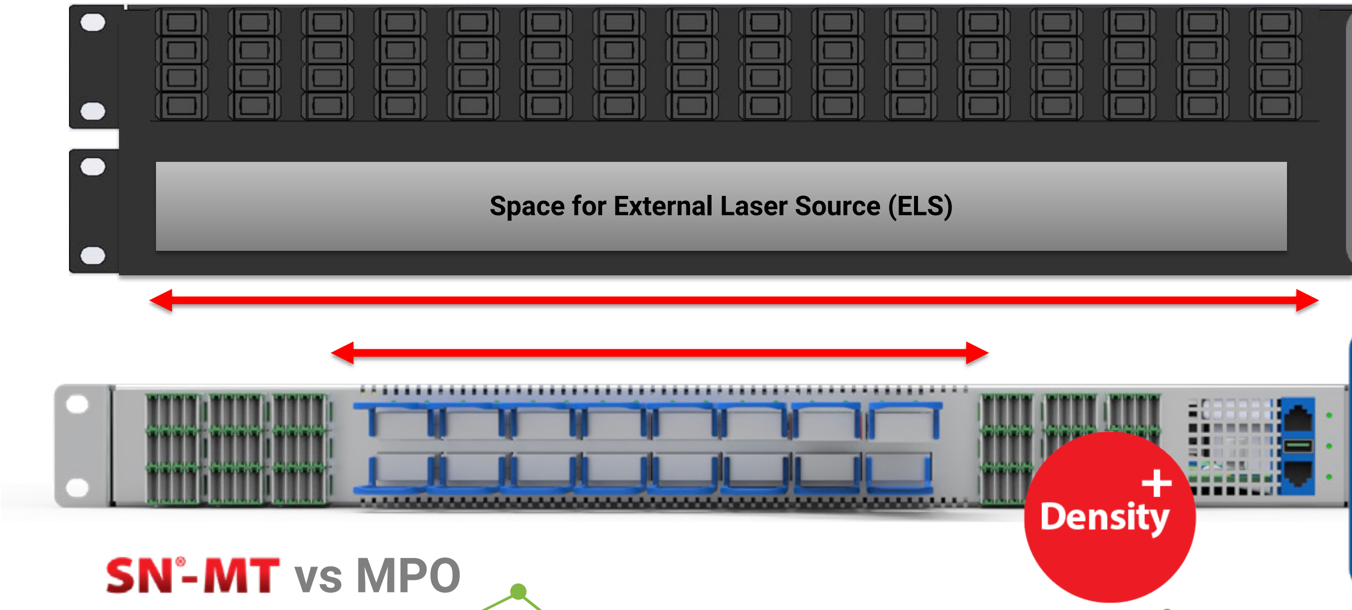
ELSFP *Host and Module* *CONNECTORS*

The Trend toward Co-Packaged Optics

Greater power savings
with CPO and On-Board



Co-Packaged Optics Faceplate Density



64 x MPO®
Total Capacity
64-Port
1,026 F
(2RU single sided rack/ cabinet)

16 x SN®-MT
Total Capacity
64-Port
1,024F
(1RU single sided rack/ cabinet)

SN®-MT vs MPO

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